

Title (en)

Copper, copper alloy, and manufacturing method therefor

Title (de)

Kupfer sowie Kupferlegierung und Verfahren zur Herstellung

Title (fr)

Cuivre et alliage de cuivre et procédé de fabrication

Publication

EP 1245690 A1 20021002 (EN)

Application

EP 02006886 A 20020326

Priority

JP 2001091179 A 20010327

Abstract (en)

Copper and copper alloy comprises: a structure having fine crystal grains with grain size of 1 μm or less after a final cold rolling with a reduction η , wherein η is expressed in the following formula and satisfying $\eta \geq 3$; and an elongation of 2% or more in a tensile test. $\langle DF \rangle \eta = \ln (T_0 / T_1)$ $\langle DF \rangle$ T_0 : plate thickness before rolling, T_1 : plate thickness after rolling. <IMAGE>

IPC 1-7

C22F 1/08; **B21B 3/00**

IPC 8 full level

C22C 9/00 (2006.01); **B21B 3/00** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP KR US)

B21B 3/00 (2013.01 - EP US); **C22C 9/00** (2013.01 - KR); **C22F 1/08** (2013.01 - EP US); **B21B 2003/005** (2013.01 - EP US)

Citation (search report)

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DOCDB simple family (publication)

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